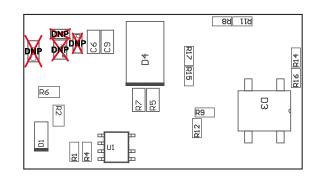


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

| PCB VIEWED FROM TOP SIDE | BOARD #: PMP11090 | REV: A | SUN REU | : Not In VersionControl | | |
|----------------------------------|--------------------|---------|---------|-------------------------|--|--|
| | TID #: | | | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 4/17/2 | 2:02:45 | PM | TEXAS INSTRUMENTS | | |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

| PCB VIEWED FROM BOTTOM SIDE | BOARD #: PMP11090 | REV: A | SUN REU: N | Not In VersionControl | |
|-------------------------------------|--------------------|---------|------------|-----------------------|--|
| | TID #: PMP11090 | | | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 4/17/2 | 2:02:46 | PM | TEXAS INSTRUMENTS | |

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